

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.21331	100.0	3.2
			<b>Subtotal</b>	<b>0.21331</b>	<b>100</b>	<b>3.2</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34442	100.0	5.167
			<b>Subtotal</b>	<b>0.34442</b>	<b>100</b>	<b>5.167</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00979	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00653	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00979	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03591	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.58638	99.81	488.8594
			<b>Subtotal</b>	<b>32.6484</b>	<b>100</b>	<b>489.79001</b>
Mould Compound	Additive	Cristobalite	14464-46-1	0.33277	0.5	4.9922
	Filler	Silica fused	60676-86-0	54.57427	82.0	818.7208
	Polymer	Phenolic resin		3.3277	5.0	49.922
	Flame retardant	Metal hydroxide		2.66216	4.0	39.9376
	Pigment	Carbon black	1333-86-4	0.33277	0.5	4.9922
	Polymer	Epoxy resin system		5.32432	8.0	79.8752
			<b>Subtotal</b>	<b>66.55399</b>	<b>100</b>	<b>998.44</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01883	10.0	0.28256
	Silver alloy	Silver (Ag)	7440-22-4	0.00377	2.0	0.05651
	Lead alloy	Lead (Pb)	7439-92-1	0.16575	88.0	2.48653
			<b>Subtotal</b>	<b>0.18835</b>	<b>100</b>	<b>2.8256</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.05152	100.0	0.77295
			<b>Subtotal</b>	<b>0.05152</b>	<b>100</b>	<b>0.77295</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>1500.19556</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.